

IC Advanced Packaging Equipments-North America Market Status and Trend Report 2013-2023

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Abstracts

Report Summary

IC Advanced Packaging Equipments-North America Market Status and Trend Report 2013-2023 offers a comprehensive analysis on IC Advanced Packaging Equipments industry, standing on the readers' perspective, delivering detailed market data and penetrating insights. No matter the client is industry insider, potential entrant or investor, the report will provide useful data and information. Key questions answered by this report include:

Whole North America and Regional Market Size of IC Advanced Packaging Equipments 2013-2017, and development forecast 2018-2023

Main market players of IC Advanced Packaging Equipments in North America, with company and product introduction, position in the IC Advanced Packaging Equipments market

Market status and development trend of IC Advanced Packaging Equipments by types and applications

Cost and profit status of IC Advanced Packaging Equipments, and marketing status

Market growth drivers and challenges

The report segments the North America IC Advanced Packaging Equipments market as:

North America IC Advanced Packaging Equipments Market: Regional Segment Analysis (Regional Consumption Volume, Consumption Volume, Revenue and Growth Rate 2013-2023):

United States

Canada

Mexico

North America IC Advanced Packaging Equipments Market: Product Type Segment Analysis (Consumption Volume, Average Price, Revenue, Market Share and Trend 2013-2023):

Die-Level Packaging Equipment

Wafer-Level Packaging Equipment

North America IC Advanced Packaging Equipments Market: Application Segment Analysis (Consumption Volume and Market Share 2013-2023; Downstream Customers and Market Analysis)

IDM

OSAT

North America IC Advanced Packaging Equipments Market: Players Segment Analysis (Company and Product introduction, IC Advanced Packaging Equipments Sales Volume, Revenue, Price and Gross Margin):

ASM Pacific

Applied Materials

Kulicke & Soffa

BESI, Inc

Advantest

Hitachi High-Technologies

Teradyne

Disco

Towa

Hanmi

PFSA

Suss Microtec

Shinkawa

Tokyo Seimitsu

Ultratech

In a word, the report provides detailed statistics and analysis on the state of the industry; and is a valuable source of guidance and direction for companies and individuals interested in the market.

Contents

CHAPTER 1 OVERVIEW OF IC ADVANCED PACKAGING EQUIPMENTS

- 1.1 Definition of IC Advanced Packaging Equipments in This Report
- 1.2 Commercial Types of IC Advanced Packaging Equipments
 - 1.2.1 Die-Level Packaging Equipment
 - 1.2.2 Wafer-Level Packaging Equipment
- 1.3 Downstream Application of IC Advanced Packaging Equipments
 - 1.3.1 IDM
 - 1.3.2 OSAT
- 1.4 Development History of IC Advanced Packaging Equipments
- 1.5 Market Status and Trend of IC Advanced Packaging Equipments 2013-2023
 - 1.5.1 North America IC Advanced Packaging Equipments Market Status and Trend 2013-2023
 - 1.5.2 Regional IC Advanced Packaging Equipments Market Status and Trend 2013-2023

CHAPTER 2 NORTH AMERICA MARKET STATUS AND FORECAST BY REGIONS

- 2.1 Market Status of IC Advanced Packaging Equipments in North America 2013-2017
- 2.2 Consumption Market of IC Advanced Packaging Equipments in North America by Regions
 - 2.2.1 Consumption Volume of IC Advanced Packaging Equipments in North America by Regions
 - 2.2.2 Revenue of IC Advanced Packaging Equipments in North America by Regions
- 2.3 Market Analysis of IC Advanced Packaging Equipments in North America by Regions
 - 2.3.1 Market Analysis of IC Advanced Packaging Equipments in United States 2013-2017
 - 2.3.2 Market Analysis of IC Advanced Packaging Equipments in Canada 2013-2017
 - 2.3.3 Market Analysis of IC Advanced Packaging Equipments in Mexico 2013-2017
- 2.4 Market Development Forecast of IC Advanced Packaging Equipments in North America 2018-2023
 - 2.4.1 Market Development Forecast of IC Advanced Packaging Equipments in North America 2018-2023
 - 2.4.2 Market Development Forecast of IC Advanced Packaging Equipments by Regions 2018-2023

CHAPTER 3 NORTH AMERICA MARKET STATUS AND FORECAST BY TYPES

3.1 Whole North America Market Status by Types

3.1.1 Consumption Volume of IC Advanced Packaging Equipments in North America by Types

3.1.2 Revenue of IC Advanced Packaging Equipments in North America by Types

3.2 North America Market Status by Types in Major Countries

3.2.1 Market Status by Types in United States

3.2.2 Market Status by Types in Canada

3.2.3 Market Status by Types in Mexico

3.3 Market Forecast of IC Advanced Packaging Equipments in North America by Types

CHAPTER 4 NORTH AMERICA MARKET STATUS AND FORECAST BY DOWNSTREAM INDUSTRY

4.1 Demand Volume of IC Advanced Packaging Equipments in North America by Downstream Industry

4.2 Demand Volume of IC Advanced Packaging Equipments by Downstream Industry in Major Countries

4.2.1 Demand Volume of IC Advanced Packaging Equipments by Downstream Industry in United States

4.2.2 Demand Volume of IC Advanced Packaging Equipments by Downstream Industry in Canada

4.2.3 Demand Volume of IC Advanced Packaging Equipments by Downstream Industry in Mexico

4.3 Market Forecast of IC Advanced Packaging Equipments in North America by Downstream Industry

CHAPTER 5 MARKET DRIVING FACTOR ANALYSIS OF IC ADVANCED PACKAGING EQUIPMENTS

5.1 North America Economy Situation and Trend Overview

5.2 IC Advanced Packaging Equipments Downstream Industry Situation and Trend Overview

CHAPTER 6 IC ADVANCED PACKAGING EQUIPMENTS MARKET COMPETITION STATUS BY MAJOR PLAYERS IN NORTH AMERICA

6.1 Sales Volume of IC Advanced Packaging Equipments in North America by Major

Players

6.2 Revenue of IC Advanced Packaging Equipments in North America by Major Players

6.3 Basic Information of IC Advanced Packaging Equipments by Major Players

6.3.1 Headquarters Location and Established Time of IC Advanced Packaging Equipments Major Players

6.3.2 Employees and Revenue Level of IC Advanced Packaging Equipments Major Players

6.4 Market Competition News and Trend

6.4.1 Merger, Consolidation or Acquisition News

6.4.2 Investment or Disinvestment News

6.4.3 New Product Development and Launch

CHAPTER 7 IC ADVANCED PACKAGING EQUIPMENTS MAJOR MANUFACTURERS INTRODUCTION AND MARKET DATA

7.1 ASM Pacific

7.1.1 Company profile

7.1.2 Representative IC Advanced Packaging Equipments Product

7.1.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of ASM Pacific

7.2 Applied Materials

7.2.1 Company profile

7.2.2 Representative IC Advanced Packaging Equipments Product

7.2.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of Applied Materials

7.3 Kulicke & Soffa

7.3.1 Company profile

7.3.2 Representative IC Advanced Packaging Equipments Product

7.3.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of Kulicke & Soffa

7.4 BESI, Inc

7.4.1 Company profile

7.4.2 Representative IC Advanced Packaging Equipments Product

7.4.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of BESI, Inc

7.5 Advantest

7.5.1 Company profile

7.5.2 Representative IC Advanced Packaging Equipments Product

7.5.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of

Advantest

7.6 Hitachi High-Technologies

7.6.1 Company profile

7.6.2 Representative IC Advanced Packaging Equipments Product

7.6.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of Hitachi High-Technologies

7.7 Teradyne

7.7.1 Company profile

7.7.2 Representative IC Advanced Packaging Equipments Product

7.7.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of Teradyne

7.8 Disco

7.8.1 Company profile

7.8.2 Representative IC Advanced Packaging Equipments Product

7.8.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of Disco

7.9 Towa

7.9.1 Company profile

7.9.2 Representative IC Advanced Packaging Equipments Product

7.9.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of Towa

7.10 Hanmi

7.10.1 Company profile

7.10.2 Representative IC Advanced Packaging Equipments Product

7.10.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of Hanmi

7.11 PFSA

7.11.1 Company profile

7.11.2 Representative IC Advanced Packaging Equipments Product

7.11.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of PFSA

7.12 Suss Microtec

7.12.1 Company profile

7.12.2 Representative IC Advanced Packaging Equipments Product

7.12.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of Suss Microtec

7.13 Shinkawa

7.13.1 Company profile

7.13.2 Representative IC Advanced Packaging Equipments Product

7.13.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of Shinkawa

7.14 Tokyo Seimitsu

7.14.1 Company profile

7.14.2 Representative IC Advanced Packaging Equipments Product

7.14.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of Tokyo Seimitsu

7.15 Ultratech

7.15.1 Company profile

7.15.2 Representative IC Advanced Packaging Equipments Product

7.15.3 IC Advanced Packaging Equipments Sales, Revenue, Price and Gross Margin of Ultratech

CHAPTER 8 UPSTREAM AND DOWNSTREAM MARKET ANALYSIS OF IC ADVANCED PACKAGING EQUIPMENTS

8.1 Industry Chain of IC Advanced Packaging Equipments

8.2 Upstream Market and Representative Companies Analysis

8.3 Downstream Market and Representative Companies Analysis

CHAPTER 9 COST AND GROSS MARGIN ANALYSIS OF IC ADVANCED PACKAGING EQUIPMENTS

9.1 Cost Structure Analysis of IC Advanced Packaging Equipments

9.2 Raw Materials Cost Analysis of IC Advanced Packaging Equipments

9.3 Labor Cost Analysis of IC Advanced Packaging Equipments

9.4 Manufacturing Expenses Analysis of IC Advanced Packaging Equipments

CHAPTER 10 MARKETING STATUS ANALYSIS OF IC ADVANCED PACKAGING EQUIPMENTS

10.1 Marketing Channel

10.1.1 Direct Marketing

10.1.2 Indirect Marketing

10.1.3 Marketing Channel Development Trend

10.2 Market Positioning

10.2.1 Pricing Strategy

10.2.2 Brand Strategy

10.2.3 Target Client

10.3 Distributors/Traders List

CHAPTER 11 REPORT CONCLUSION

CHAPTER 12 RESEARCH METHODOLOGY AND REFERENCE

12.1 Methodology/Research Approach

12.1.1 Research Programs/Design

12.1.2 Market Size Estimation

12.1.3 Market Breakdown and Data Triangulation

12.2 Data Source

12.2.1 Secondary Sources

12.2.2 Primary Sources

12.3 Reference

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